



Click [here](#) for the 3D model.

Dimensions

Chip Size	1812
L	4.572mm +/-0.381mm (0.18 in +/-0.015 in)
W	3.175mm +/-0.381mm (0.125 in +/-0.015 in)
T	2.032mm MAX (0.08 in MAX)

Packaging Specifications

Packaging	Waffle
Packaging Quantity	25000

General Information

Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Ultra Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
Termination	Nickel
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3000 pF
Capacitance Tolerance	10%
Voltage DC	100 VDC
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

单击下面可查看定价，库存，交付和生命周期等信息

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